



SBOS301 - MAY 2004

Single-Supply, High-Speed, Precision LOGARITHMIC AMPLIFIER

FEATURES

- **EASY-TO-USE COMPLETE FUNCTION**
- TWO OUTPUT, WIDE BW SCALING **AMPLIFIERS**
- WIDE INPUT DYNAMIC RANGE: 8 Decades, 100pA to 10mA
- 2.5V REFERENCE
- **EXCELLENT GAIN STABILITY OVER TEMPERATURE**
- **LOW QUIESCENT CURRENT: 10mA**
- DUAL OR SINGLE SUPPLY: ±5V, +5V
- PACKAGE: Small QFN-16 (4mm x 4mm)
- SPECIFIED TEMPERATURE RANGE: -5°C to +75°C

APPLICATIONS

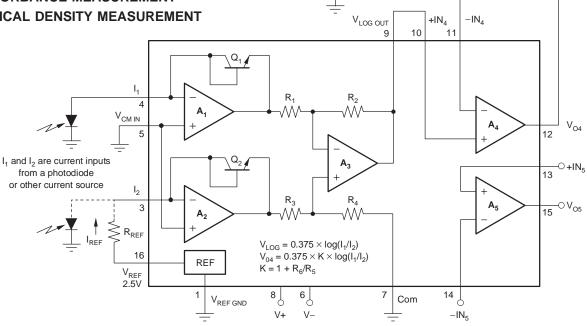
- LOG, LOG-RATIO FUNCTION FOR TEST, **GENERAL INSTRUMENTATION**
- PHOTODIODE SIGNAL COMPRESSION AMP
- **ANALOG SIGNAL COMPRESSION IN FRONT** OF ANALOG-TO-DIGITAL CONVERTER (ADC)
- ABSORBANCE MEASUREMENT
- **OPTICAL DENSITY MEASUREMENT**

DESCRIPTION

The LOG114 computes the logarithm or log-ratio of an input current or voltage relative to a reference current or voltage.

High precision is ensured over a wide dynamic range of input signals on either bipolar or single supply. Special temperature drift compensation circuitry is included on-chip. In log-ratio applications, a signal current can come from a photodiode, and a reference current from a resistor in series with a precision internal voltage

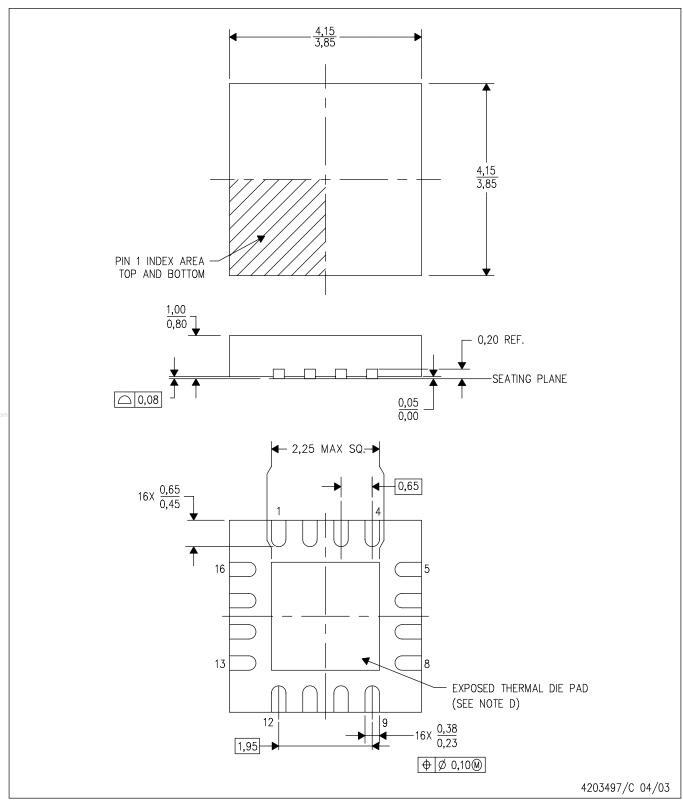
The output signal at V_{I OGOUT} is trimmed to 0.375V out per decade of input current. If more range is needed, the supply voltage can be increased on the LOG114 and the output can be scaled with one of the available additional amplifiers, if desired. Low dc offset voltage and temperature drift allow accurate measurement of low-level signals over a wide environmental temperature range. The LOG114 is specified over a −5°C to +75°C temperature range.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.





NOTES: A. All linear dimensions are in millimeters.

- This drawing is subject to change without notice.
- Quad Flatpack, No—leads (QFN) package configuration.
 The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane.
- E. Falls within JEDEC MO-220.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

	Applications	
amplifier.ti.com	Audio	www.ti.com/audio
dataconverter.ti.com	Automotive	www.ti.com/automotive
dsp.ti.com	Broadband	www.ti.com/broadband
interface.ti.com	Digital Control	www.ti.com/digitalcontrol
logic.ti.com	Military	www.ti.com/military
power.ti.com	Optical Networking	www.ti.com/opticalnetwork
microcontroller.ti.com	Security	www.ti.com/security
	Telephony	www.ti.com/telephony
	Video & Imaging	www.ti.com/video
	Wireless	www.ti.com/wireless
	dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com	amplifier.ti.com dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com Audio Automotive Broadband Digital Control Military Power.ti.com Security Telephony Video & Imaging

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2004, Texas Instruments Incorporated